

ABSTRACT

The object of the present invention is a method of coating a surface of a substrate with copper by electroplating.

According to the invention, this method comprises:

- a step during which the said surface to be coated is brought into contact with an electroplating bath while the said surface is not under electrical bias;

- a step of forming the coating during which the said surface is biased;

- a step during which the said surface is separated from the electroplating bath while it is under electrical bias;

the aforementioned electroplating bath comprising, in solution in a solvent:

- a source of copper ions, with a concentration of between 0.4 and 40mM; and

- at least one copper complexing agent.